Compliant with IEC 62474/ D9.00

Compliant to IEC 61249-2-21:2003

MICROCHIP			Termination Base Alloy: Copper Alloy (Cu)			Package Homogeneous Materials: 8.1 Electronics (e.g. pc boards, displays)			J-STD-609A Product Marking and/or Pkg. Labeling e3	
Semiconductor Device Type: 48 TQFP 7x7x1.0mm Matte Tin (CQA)				!						
Basic Substance	CAS Number	"Contained In" Sub-Component	% Total Weight	mg/part	ppm	84.75	(mg) Total	Mold Compound	% ot Total Weight	67.69
Fused Silica	60676-86-0	Mold Compound	57.266	71.697	572,657		Fused Silica	60676-86-0	84.60	
Epoxy Resin	Trade Secret	Mold Compound	3.994	5.000	39,937		Epoxy Resin	Trade Secret	5.90	1
Metal Hydroxide	Trade Secret	Mold Compound	3.858	4.831	38,583		Metal Hydroxide	Trade Secret	5.70	
Phenol Resin	Trade Secret	Mold Compound	2.437	3.051	24,368		Phenol Resin	Trade Secret	3.60	
Carbon Black	1333-86-4	Mold Compound	0.135	0.169	1,354		Carbon Black	1333-86-4	0.20	
Copper	7440-50-8	Lead Frame	25.677	32.148	256,770			Total	100.00	Ī
Nickel	7440-02-0	Lead Frame	0.685	0.857	6,848	33.75	(mg) Total	Lead Frame	% of Total Weight	26.96
Silver	7440-22-4	Lead Frame	0.450	0.563	4,500		Copper	7440-50-8	95.24	
Silicon	7440-21-3	Lead Frame	0.121	0.152	1,213		Nickel	7440-02-0	2.54	1
Magnesium	7439-95-4	Lead Frame	0.027	0.034	270		Silver	7440-22-4	1.67	
Silver	7440-22-4	Die Attach	0.061	0.076	608		Silicon	7440-21-3	0.45	
Epoxy resin	Trade Secret	Die Attach	0.016	0.020	160		Magnesium	7439-95-4	0.10	
Copper	7440-50-8	Die Attach	0.003	0.004	32			Total	100.00	Ī
Silicon	7440-21-3	Chip (Die)	0.940	1.177	9,400	0.10	(mg) Total	Die Attach	% of Total Weight	0.08
Gold	7440-57-5	Wire Bond	0.790	0.989	7,900		Silver	7440-22-4	76.00	
Tin	7440-31-5	Plating on external leads (pins) - Matte Tin / annealed at 150°C for 1 hour	3.540	4.432	35,400		Epoxy resin	Trade Secret	20.00	
		TOTALS:	100.000	125.200	1,000,000		Copper	7440-50-8	4.00	
	0.1252	g Total Mass						Total	100.00	Ī
This semiconductor device and its homogenous materials comply with EU Directives: 2002/95/EC (27 January 2003) & Directive 2011/65/EU (08 June 2011) and 2015/863/EU (31 March 2015) and 2002/53/EC (End-of-Life Vehicles (ELV) without exemption (zero) Compliance with the above EU Directives has been verified via internal design controls, supplier declarations, and /or analytical test data. If a chemical substance is absent from the list above, the chemical substance is NOT an intentional ingredient in the semiconductor device and, to the best of Microchip Technology						1.18	Total (mg) Doped Silicon	7440-21-3 Total	% of Total Weight 100.00 100.00	
corporated's knowledge and belief as of the date of this docume elow the threshold of regulatory concern for any regulatory sch olding compounds used by Microchip meet the ULy4 V6 flamm ttp://ul.com/global/eng/pages/offerings/industries/chemicals/pla	eme world-wide. ability standard for p				nce, if any, is not	0.99	(mg) Total	Wire Bond	% of Total Weight	: 0.79
The protective "tubes" in which the specific product is shipped are made from polyvinyl chloride (PVC) plastic. "Window envelopes" used to hold the packing slip on the outer box and certain "reels" may be made from PVC plastic.							Gold	7440-57-5	100.00	
icrochip Technology Incorporated believes the information in triginal packing materials is true and correct to the best of its kn d accuracy of data in this form because it has been compiled I rotected from disclosure as trade secrets and some informatior if the average weight of these parts and the average weight of a aterials contained within silicon devices (silicon IC) in the finis	owledge and belief, ased on the ranges may not have been ticipated significant	as of the date listed in this form. Microchip Technology provided in Material Safety Data Sheets provided by raw provided by subcontract assemblers and raw material su	ncorporated cannot material suppliers. Suppliers. Suppliers. Information	guarantee the Supplier infor is provided o	e completeness mation is often only as estimates			Total	100.00	
Microchip Technology Incorporated does not provide any warranty, express or implied, with respect to the information provided in this declaration. The exclusive, limited product warranties provided by Microchip Technology Incorporated and its subsidiaries are contained in Microchip's standard terms and conditions of sale. These are provided in Microchip's quotations, sales order acknowledgement, and invoices.						4.43	(mg) Total	Plating on external leads (pins) - Matte Tin / annealed at 150°C for 1 hour	% of Total Weight	3.54
Microchip disclaims any duty to notify users of updates or changes to Material Content Declarations and shall not be liable for any damages, direct or indirect, consequential or otherwise, suffered by users or third parties as a result of the users' reliance on the information in Material Content Declarations (MCD) or independent third party test reports (SGS) or of this Certificate of Compliance for semiconductor products.							Tin	7440-31-5	100.00	
		,						Total	100.00]

Au 14:45 : 04/18/16